COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
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<tr>
<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: PMP20676</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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</thead>
<tbody>
<tr>
<td>TID #: N/A</td>
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PLOT NAME = Top Assembly Drawing
GENERATED : 1/4/2017 2:37:15 PM
TEXAS INSTRUMENTS
Components marked 'DNP' should not be populated.
Assembly Variant: 001

<table>
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<th>PCB Viewed from Bottom Side</th>
<th>Board #: PMP20676</th>
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<th>SUN REV: Not In VersionControl</th>
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Plot Name = Bottom Assembly Drawing

Generated: 1/4/2017 2:37:16 PM

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